



Material Content Data Sheet



Sales Product Name		BTM7752G		Issued		27. September 2017		
MA#		MA000732602						
Package		PG-DSO-36-29		Weight*		616.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.155	0.51	0.51	5120	5120
leadframe	inorganic material	phosphorus	7723-14-0	0.055	0.01		89	
	non noble metal	zinc	7440-66-6	0.220	0.04		356	
	non noble metal	iron	7439-89-6	4.391	0.71		7126	
wire	non noble metal	copper	7440-50-8	178.313	28.93	29.69	289331	296902
	noble metal	gold	7440-57-5	0.366	0.06		595	
	non noble metal	aluminium	7429-90-5	2.431	0.39	0.45	3944	4539
encapsulation	organic material	carbon black	1333-86-4	0.836	0.14		1356	
	plastics	epoxy resin	-	59.764	9.70		96973	
	inorganic material	silicondioxide	60676-86-0	357.330	57.98	67.82	579804	678133
leadfinish	non noble metal	tin	7440-31-5	4.833	0.78	0.78	7842	7842
plating	noble metal	silver	7440-22-4	2.839	0.46	0.46	4607	4607
glue	plastics	epoxy resin	-	0.308	0.05		500	
	noble metal	silver	7440-22-4	1.452	0.24	0.29	2357	2857
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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